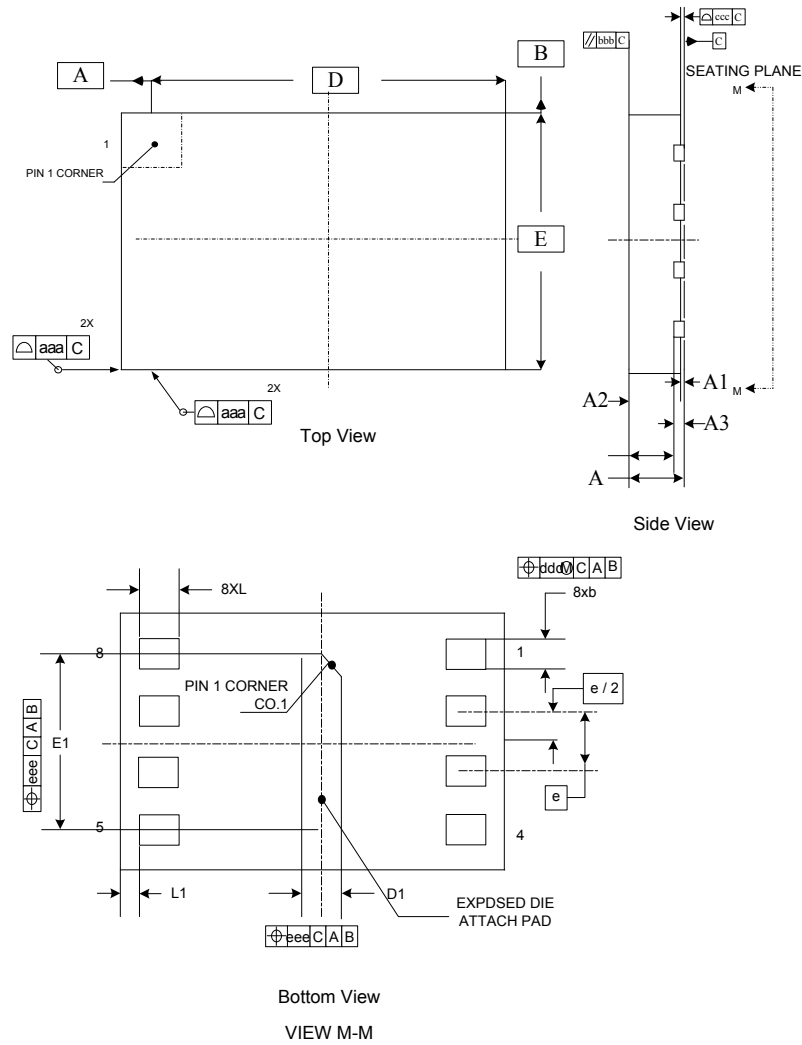


厚度为 0.45mm 封装

USON8 (3×2mm) (3,000个/ 卷)

Unit : mm



Dimensions

Symbol		A	A1	A2	A3	b	D	E	e	J	K	L
Unit												
mm	Min	0.40	0.00	0.25	0.150 REF	0.20	2.90	1.90	0.5 BSC	0.15	1.55	0.30
	Nom	0.45	-	0.30		0.25	3.00	2.00		0.20	1.60	0.35
	Max	0.50	0.05	0.35		0.30	3.10	2.10		0.25	1.65	0.40
Inch	Min	0.015	0.00	0.009	0.005 REF	0.007	0.114	0.074	0.019 BSC	0.005	0.061	0.011
	Nom	0.018	-	0.012		0.010	0.118	0.079		0.008	0.063	0.014
	Max	0.019	0.001	0.013		0.012	0.122	0.082		0.009	0.064	0.015

Note:

- Both package length and width do not include mold flash.
- The exposed metal pad area on the bottom of the package is connected to device ground (GND pin), so both Floating and connecting GND of exposed pad are also available.